Call for Papers, Workshops, Tutorials, Special Sessions

• CASES • CODES+ISSS • EMSOFT • MEMOCODE • Workshops • Tutorials •

About Embedded Systems Week (ESWEEK)

Embedded Systems Week (ESWEEK) is the premier international event covering all aspects of hardware and software design for intelligent and connected computing systems. By bringing together three leading conferences (CASES, CODES+ISSS, EMSOFT), one symposium (MEMOCODE), and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development.

One Registration, three Conferences!

Registered attendees can attend sessions in any of the ESWEEK conferences (CASES, CODES+ISSS, EMSOFT). Please note that tutorials, symposia (MEMOCODE), and workshops may use separate registration.

Journal Track:
  Abstract Submission: March 24, 2024
  Full Paper Submission: March 31, 2024 (firm)
  Notification of Acceptance: July 14, 2024

Late Breaking and Work-in-Progress Tracks:
  Paper Submission: June 2, 2024 (firm)
  Notification of Acceptance: June 30, 2024

Proposals of Workshops, Tutorials, Education Classes, and Special Sessions: March 24, 2024

All submissions are due by midnight, AOE.

International Conference on Compilers, Architectures, and Synthesis for Embedded Systems

CASES is a premier forum where researchers, developers and practitioners exchange information on the latest advances in compilers and architectures for high-performance, low-power embedded systems. The conference has a long tradition of showcasing leading-edge research in embedded processor, memory, interconnect, storage architectures and related compiler techniques targeting performance, power, predictability, security, reliability issues for both traditional and emerging application domains. In addition, we invite innovative papers that address design, synthesis, and optimization challenges in heterogeneous and accelerator-rich architectures.

International Conference on Hardware/Software Codesign and System Synthesis

The International Conference on Hardware/Software Co-design and System Synthesis (CODES+ISSS) is the premier event in system-level design, modeling, analysis, and implementation of modern embedded and cyber-physical systems, from system-level specification and optimization down to system synthesis of multi-processor hardware/software implementations. The conference is a forum bringing together academic research and industrial practice for all aspects related to system-level and hardware/software co-design.
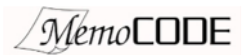
Symposia

Tutorials

Workshops

Keynotes

International Conference on Embedded Software

The ACM SIGBED International Conference on Embedded Software (EMSOFT) brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

International Symposium on Formal Methods and Models for System Design

MEMOCODE focuses on formal methods and models for developing computer systems and their components. MEMOCODE's objective is to emphasize the importance of models and methodologies in correct system design and development.

Journal-Integrated Publication Model: All full papers accepted in one of the three conferences will be published in **IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)**. All late-breaking papers accepted in one of the three conferences will be published in **IEEE Embedded Systems Letters (ESL)**.

www.esweek.org

Paper Process

ESWEEK 2024 has three publication venues. **(1) Journal Track**: Full-length papers describing mature work limited to 12 pages in IEEE double-column format. Accepted papers will be published in IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD) after two stages of review. Articles not accepted after the second review stage will still have the possibility of continuing as regular journal papers in TCAD (pending a decision from the TPC chairs). **(2) Late Breaking (LB) Result Track**: LB papers describing mature work and limited to 4 pages in IEEE double-column format. Accepted papers will be published in IEEE Embedded Systems Letters (ESL) after one stage of review. Articles not accepted after this review stage will still have the possibility of continuing as regular journal papers in ESL (pending a decision from the TPC chairs). **(3) Work-in-Progress (WiP) Track**: WiP papers presenting not-yet-mature-but-promising research work, limited to an extended abstract of 1 page in IEEE double-column format. Accepted WiP papers will be published in the ESWEEK proceedings of CASES, CODES+ISSS, or EMSOFT depending on where they have been submitted. These three venues (full-length, LB, WiP), are mutually exclusive. For more information on the publishing process, please refer to
http://www.esweek.org/author-information.

Workshops, Tutorials, Special Sessions

Call for Workshop Proposals
ESWEEK 2024 will host several workshops on Thursday and Friday October 3 and 4, and is soliciting proposals for new and recurring workshops. Workshops can be from a half day to two days long. We invite workshop proposals on any topic related to the broad set of research and education in embedded systems, including on their role for and their impact on the environmental crisis.

Call for Tutorial Proposals
ESWEEK 2024 is looking for high-quality tutorials that will take place on Sunday, September 29, 2024. Tutorials on all topics related to embedded system design, analysis, and development are welcome. Tutorials can be either half/full-day, lecture style or hands-on.

Call for Education Proposals
ESWEEK 2024 will host several education lectures *virtually* on Thursday and Friday September 26 and 27, and is soliciting proposals for such lectures. We invite you to submit education proposals on any topic related to all aspects of design, validation, manufacturing … of embedded systems.

Call for Special Session Proposals
We invite you to submit special session proposals on any topic relevant to the broad areas of interest of ESWEEK. The special session should cover a topic that is contemporary, hot, and complementary to the regular sessions, in order to generate enthusiasm among the ESWEEK participants.

Sponsoring Societies:

ESWEEK 2024 General Chairs
Alain Girault, INRIA and Univ. Grenoble Alpes, FR
Tei-Wei Kuo, National Taiwan University, TW

ESWEEK Conference Program Chairs
CASES
Jana Doppa, Washington State University, US
Jeronimo Castrillon, TU Dresden, DE
CODES+ISSS
Muhammad Shafique, New York University, US
Prabhat Mishra, University of Florida, US
EMSOFT
Alessandro Biondi, Scuola Superiore Sant'Anna, IT
Martina Maggio, Lund Univ., SE and Saarland Univ., DE

ESWEEK Organizational Committee
Conference and Local Arrangement Chair
Frank Mueller, North Carolina State University, US
Finance Chair
Jingtong Hu, University of Pittsburgh, US
Special Sessions Chair
Pi-Cheng Hsiu, Academia Sinica, TW
Panel and Chair
Marilyn Wolf, University of Nebraska-Lincoln, US
Workshops Chair
Heiko Falk, Hamburg University of Technology, DE
Tutorials Chair
Christian Pilato, Politecnico di Milano, IT
Education Chairs
Anup Das, Drexel University, US
Qingfeng (Karen) Zhege, East China Normal University, CN
Awards Chair
Hai (Helen) Li, Duke University, US
Diversity and Inclusion Chair
Nele Mentens, KU Leuen, BE
Student Competition Chairs
Wanli Chang, Hunan University, CN
Weiwen Jiang, George Mason University, US
Ph.D. Forum Chair
Xue "Shelley" Lin, Northeastern University, US
Publication Chair
Gang Quan, Florida International University, US
Web Chair
Timothy Bourke, Inria and PSL University, FR
Registration Chair
Bo Yuan, Rutgers University, US
Publicity Chairs
Lars Bauer, Karlsruhe Institute of Technology, DE
Wei Jiang, Univ. of Elec. Sci. & Tech. of China, CN
Social Media Chair
Fanxin Kong, Syracuse University, US
YouTube Chair
To be nominated
Industry Engagement Committee
Yiran Chen, Duke University, US (**Chair**)
Hugo Andrade, AMD, US
LuLu Chan, NXP, NL
Patrick Haspel, Synopsys Inc, US
Reiley Jeyapaul, ARM, US
Yu Wang, Tsinghua University, CN
Dirk Ziegenbein, Robert Bosch GmbH, DE